

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1-8. (Canceled).

9-19. (Canceled).

20. (New) A semiconductor device comprising:

a semiconductor chip having over a main surface thereof an integrated circuit and plural electrodes;

plural leads arranged around said semiconductor chip;

plural wires for connecting the plural electrodes on said semiconductor chip with the plural leads; and

a resin sealing member for sealing said semiconductor chip, portions of said plural leads and said plural wires;

wherein the plural leads having plural first leads includes first terminal portions respectively and plural second leads includes second terminal portions respectively, the plural second leads each being disposed between adjacent ones of said first leads;

wherein end portions on one side of each of the plural first leads are positioned outside said semiconductor chip;

wherein end portions on one side of each of the plural second leads are fixed to a back surface of said semiconductor chip;

wherein the first terminal portions are arranged along side faces of the resin sealing member respectively; and

wherein the second terminal portions are arranged inside said first terminal portions respectively.

21. (New) The semiconductor device according to claim 20, wherein said semiconductor chip is fixed to the end portions on one side of each of the plural second leads through a base which has a main surface and a back side.

22. (New) The semiconductor device according to claim 21, wherein the end portions on one side of each of the plural second leads are fixed to the back side of the base.

23. (New) The semiconductor device according to claim 22, wherein the base is exposed from the resin sealing member.

24. (New) The semiconductor device according to claim 20, wherein the plural leads each have a first portion, a second portion bent from the first portion to a back surface of the resin sealing member, and a third portion extending from the second portion toward the side face of the resin sealing member.

25. (New) The semiconductor device according to claim 24, wherein said semiconductor chip is fixed to the first portion; and

wherein the first terminal portions and the second terminal portions are formed in the third portion.

26. (New) The semiconductor device according to claim 20, wherein the plural leads are fixed to said semiconductor chip through an adhesive.